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INTERNATIONAL STANDARD

IEC 62137-1-1

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**Surface mounting technology –
Environmental and endurance test
methods for surface mount solder joint –**

**Part 1-1:
Pull strength test**



Commission Electrotechnique Internationale
International Electrotechnical Commission
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CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references	5
3 Terms and definitions	6
4 General remarks.....	6
5 Test equipment and materials.....	7
5.1 Flow soldering equipment.....	7
5.2 Reflow soldering equipment	7
5.3 Pull strength test equipment	7
5.4 Optical microscope.....	7
5.5 Test substrate	7
5.6 Solder alloy	8
5.7 Flux for flow soldering	8
5.8 Solder paste.....	8
6 Mounting method.....	8
6.1 Flow soldering.....	8
6.2 Reflow soldering.....	9
7 Test conditions	10
7.1 Test: Rapid change of temperature.....	10
7.2 Pull strength test	10
8 Test procedure	10
8.1 Test sequence.....	10
8.2 Pre-conditioning	11
8.3 Initial pull strength measurement.....	11
8.4 Rapid change of temperature	11
8.5 Recovery.....	11
8.6 Intermediate/final pull strength measurement	11
9 Items to be included in the test report.....	11
10 Items to be given in the product specification	12
Annex A (normative) Pull strength test – Details	13
Bibliography.....	15
Figure 1 – Gull-wing leaded component.....	6
Figure 2 – Area under evaluation in the pull strength test.....	7
Figure 3 – Example of a flow soldering profile (actual measurement for double-wave soldering)	9
Figure 4 – Typical reflow profile	10
Figure 5 – Test procedure.....	11
Figure A.1 – Pull strength test.....	14
Figure A.2 – An example of the shape of the tip of the pulling jig	14
Figure A.3 – Failure modes in pull strength test	14

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE MOUNTING TECHNOLOGY –
ENVIRONMENTAL AND ENDURANCE TEST METHODS
FOR SURFACE MOUNT SOLDER JOINT –**

Part 1-1: Pull strength test

FOREWORD

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International Standard IEC 62137-1-1 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/681/FDIS	91/697/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62137 series, under the general title *Surface mounting technology – Environmental and endurance test methods for surface mount solder joint*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

SURFACE MOUNTING TECHNOLOGY – ENVIRONMENTAL AND ENDURANCE TEST METHODS FOR SURFACE MOUNT SOLDER JOINT –

Part 1-1: Pull strength test

1 Scope

The test method described in this part of IEC 62137 is applicable to gull-wing lead surface mounting components.

The method is designed to test and evaluate the endurance of the solder joint between component leads and lands on a substrate, by means of a pull type mechanical stress. This test is suitable for evaluating the effects of repeated temperature change on the strength of the solder joint between component terminals and lands on a substrate.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1: *Environmental testing – Part 1: General and guidance*

IEC 60068-2-14: *Environmental testing – Part 2-14: Test N: Change of temperature*

IEC 60194: *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61188-5-5, *Printed boards and printed board assemblies – Design and use – Part 5-5: Sectional requirements - Attachment (land/joint) considerations – Components with gull-wing leads on four sides*¹

IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-2: *Attachment materials for electronic assembly – Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly*

IEC 61190-1-3 *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

IEC 61249-2-7, *Materials for printed boards and other interconnecting structures – Part 2-7: Reinforced base materials clad and unclad – Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad*

¹ In preparation.